

High Temperature Masking Tape

multicomp PRO



**RoHS
Compliant**

Description

High temperature masking tape is ideal for masking printed circuit boards during wave solder or solder dip process, as well as for solder wave masking and electrical insulation. The polyimide, pressure sensitive, adhesive tape with silicon resin, shows excellent dielectric insulation properties, high heat resistance and excellent solvent resistance.

These properties result in a tape with remarkable dimensional stability and excellent electrical and physical properties over a wide range of temperatures.

Features

- High heat resistance
- Excellent solvent resistance
- Neither corrosive nor ozone depleting
- 33m length

	DIN Value	ASTM Value
Structure	Silicone Adhesive / Polyimide Film	
Base Film Thickness	0.025mm	1.0MIL
Total Thickness	0.070mm	2.8MIL
Peel Strength	2.7N/CM	25oz/In
Tensile Strength	40N/CM	22lbs/In
Elongation	50%	50%
Heat Resistance (Short Term)	290°C	554°C
Heat Resistance (Long Term)	230°C	446°C
Appearance	Amber	Amber

Part Number Table

Description	Part Number	Size (mm)
High Temperature Masking Tape	MP004377	10
High Temperature Masking Tape	MP004378	14
High Temperature Masking Tape	MP004379	20

Newark.com/multicomp-pro
Farnell.com/multicomp-pro
Element14.com/multicomp-pro

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